

WHAT IS CLAIMED IS:

1. A bonding apparatus comprising:

a stage comprising a placement surface on which a substrate is to be placed;

a bonding head for disposing a chip part on the substrate placed on the stage and

5 comprising a chip holding surface for holding the chip part by suction and an adjustment part for adjusting an inclination of the chip holding surface;

an information holding part for holding inclination information of the stage that associates a position on the placement surface with an inclination at the position; and

10 a conforming jig comprising a conforming surface onto which the chip holding surface is pressed, wherein an inclination of the conforming surface is changeable such that the inclination of the chip holding surface corresponds to an inclination indicated by the inclination information.

2. The bonding apparatus according to claim 1, wherein the conforming jig comprises a passive inclination part which comprises the conforming surface and in which the conforming surface is passively inclined by a force received by the conforming surface, and

15 wherein the bonding apparatus further comprises:

a control part that acquires the inclination information from the information holding part and controls a force that the chip holding surface applies to the conforming surface based on the inclination at the position when the chip holding surface is pressed against the conforming surface.

20 3. The bonding apparatus according to claim 2, wherein the passive inclination part comprises:

a plate member comprising the conforming surface; and

an elastic deformation part provided on a surface of the plate member opposite to the conforming surface, and

the elastic deformation part is made of a resin material.

25 4. The bonding apparatus according to claim 2, wherein the passive inclination part comprises:

a plate member comprising the conforming surface; and

an elastic deformation part provided on a surface of the plate member opposite to the conforming surface, and

the elastic deformation part is a metal spring.

5            5. The bonding apparatus according to claim 1, wherein the conforming jig comprises an active inclination part which comprises the conforming surface and in which the conforming surface is actively inclined when no force is received by the conforming surface,

the active inclination part comprises:

a plate member comprising the conforming surface; and

10           a plate member drive part provided on a surface of the plate member opposite to the conforming surface and actively controlling an inclination of the plate member, and

the plate member drive part inclines the plate member such that the inclination of the conforming surface corresponds to an inclination indicated by the inclination information provided from the information holding part.

15           6. A bonding head adjustment method for adjusting an inclination of a chip holding surface of a bonding head for disposing a chip part with respect to a substrate placed on a placement surface of a stage having the placement surface on which the substrate is to be placed, wherein the chip holding surface holds the chip part by suction,

the bonding head adjustment method comprising:

20           a first step of acquiring inclination information that associates a position on the placement surface with an inclination at the position; and

a second step of adjusting the inclination of the chip holding surface based on the inclination information associated with the position on the placement surface corresponding to a position of the substrate on which the chip part is to be disposed;

25           wherein the second step adjusts the inclination of the chip holding surface using a conforming jig in which a conforming surface is passively inclined in response to pressing of the

chip holding surface.

7. A bonding head adjustment method for adjusting an inclination of a chip holding surface of a bonding head for disposing a chip part with respect to a substrate placed on a placement surface of a stage having the placement surface on which the substrate is to be placed, wherein the chip holding surface holds the chip part by suction,

the bonding head adjustment method comprising:

a first step of acquiring inclination information that associates a position on the placement surface with an inclination at the position; and

a second step of adjusting the inclination of the chip holding surface based on the inclination information associated with the position on the placement surface corresponding to a position of the substrate on which the chip part is to be disposed;

wherein the second step adjusts the inclination of the chip holding surface using a conforming jig in which a conforming surface is actively inclined when there is no pressing of the chip holding surface.